

# How to select the best gap filler solution for your application?

Ad Musters  
28 May 2024



# Thal Technologies company profile

## PERFORMANCE MATERIALS

Protect electronics with Thal Thermal Interface and insulation materials

## LED solutions

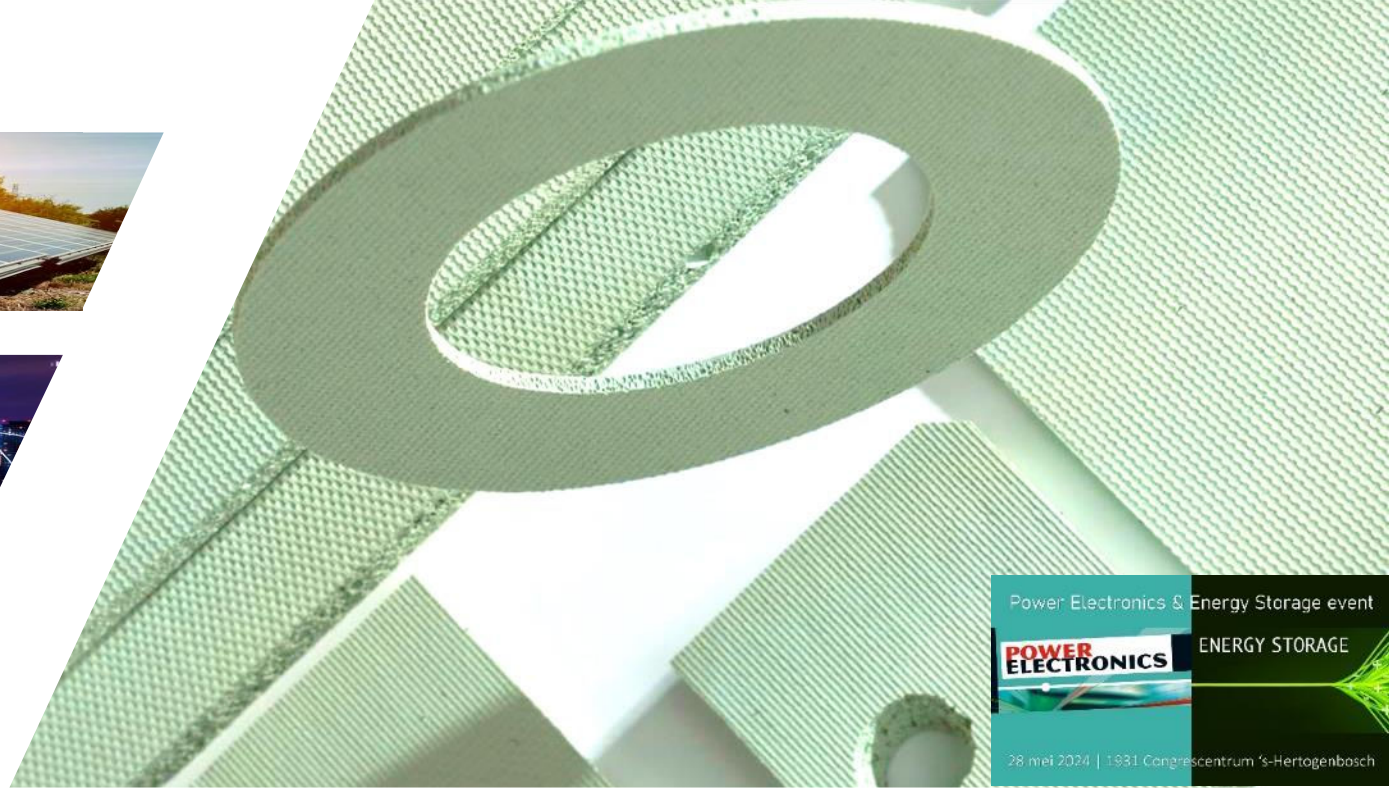
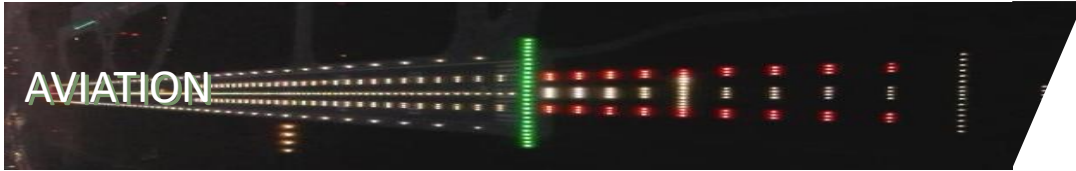
High-End Industrial LED modules design and manufacturing

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# THERMAL INTERFACE MATERIALS



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- INNOVATION
- ENGINEERING
- RESEARCH & DEVELOPMENT
- MANUFACTURING
- SUPPLY CHAIN
- TESTING
- QUALITY ASSURANCE

# Problem statement

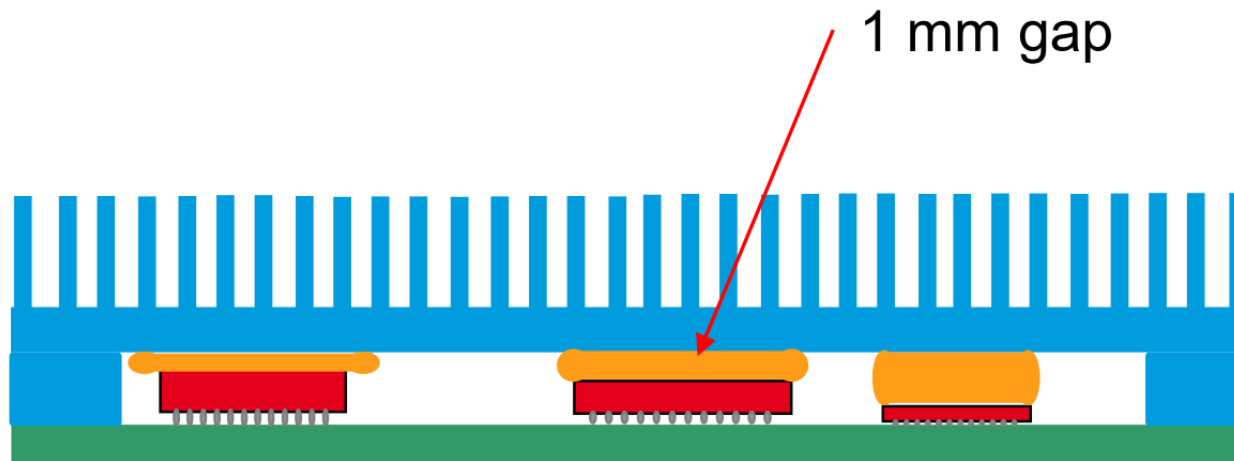


Avoid Electronic components from overheating

Meet lifetime requirement: Cool electronics last longer

Thin thermal interface materials do not fill a gap with high tolerance

Avoid fan cooling



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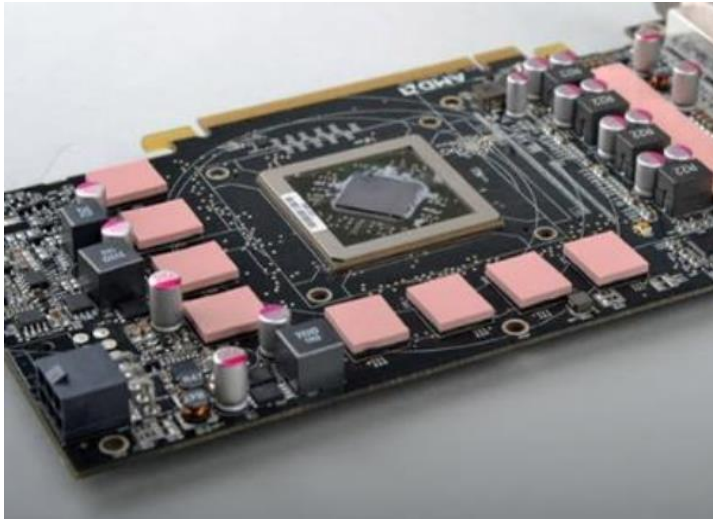
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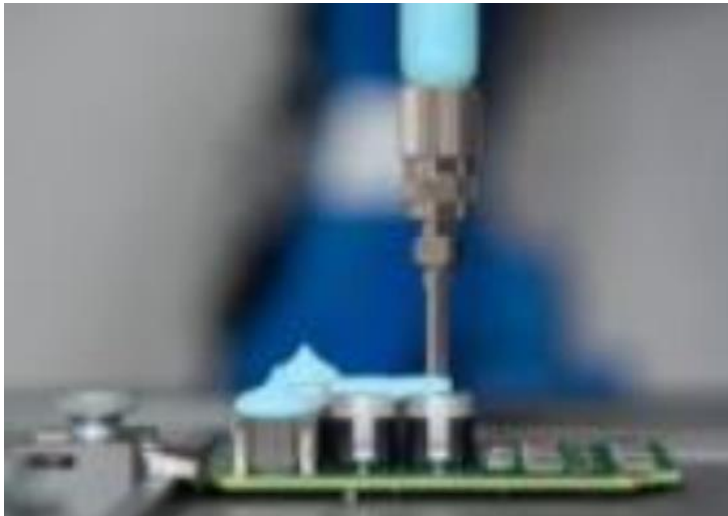
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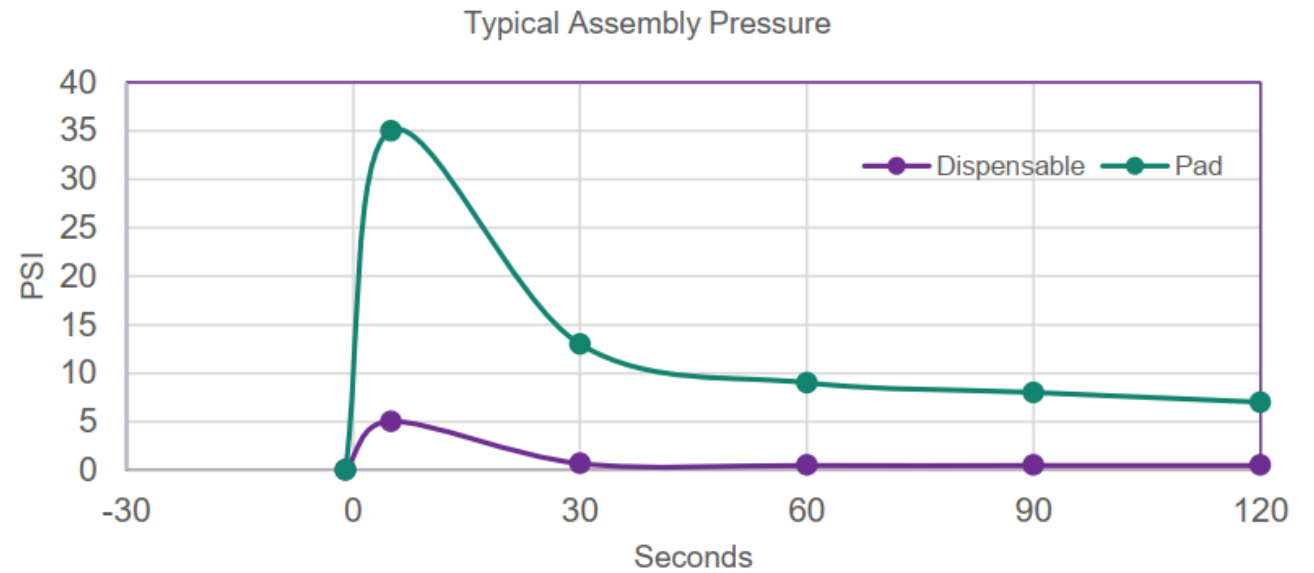


- Gap pads



- Liquid gap filler

# Type of gap fillers



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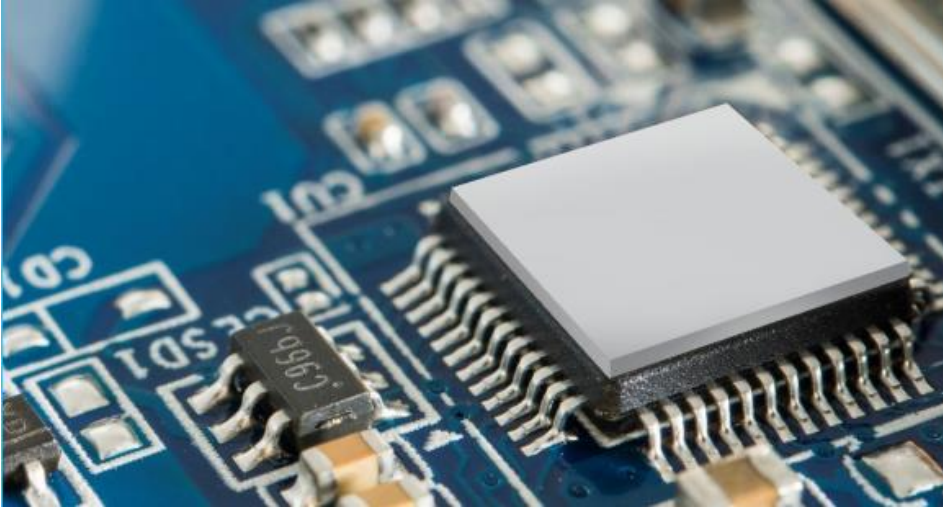
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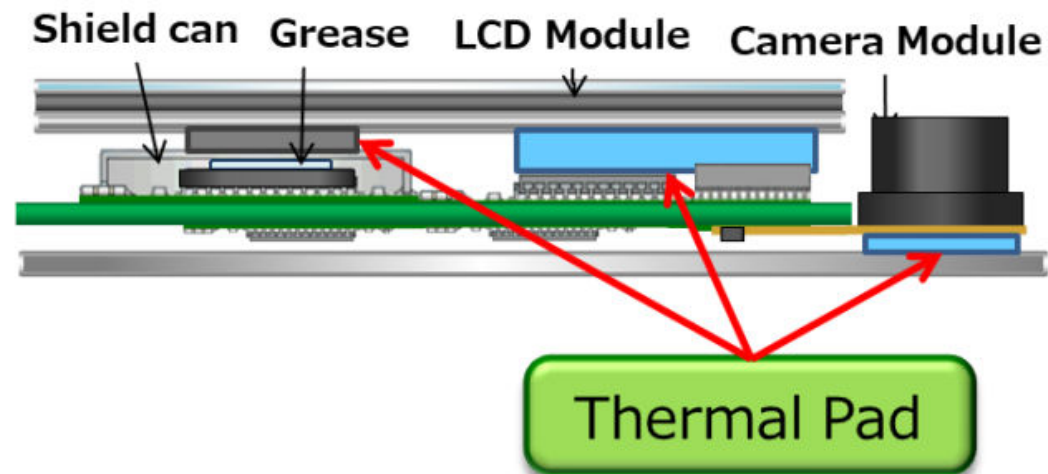
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# Gap pad types



- Silicone
- Non silicone
  - PU
  - Acrylic



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# Material selection Silicone vs PU vs Acrylic

| Property          | Silicone  | PolyUrethane | Acrylic     |
|-------------------|-----------|--------------|-------------|
| Softness          | +++       | +            | ++          |
| Temperature range | +++       | +            | ++          |
| Price *           | \$\$\$\$  | \$\$         | \$\$        |
| Lifetime (proven) | +++       | +            | ++          |
| Sustainability    | +         | ++           | +++         |
| Availability      | +++       | +            | ++          |
| Thermoset/plast   | Thermoset | Thermoplast  | Thermoplast |

\* Thermal conductive filler material may be highest cost in the material stack

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# Innovations in gap filler material

- Higher thermal conductivity
- Softer
- Trend to use, where possible, acrylic instead of silicone
- PFAS free
- Reduce or use no plasticizers (weekmakers)
- Lower abrasive fillers for liquid gap fillers



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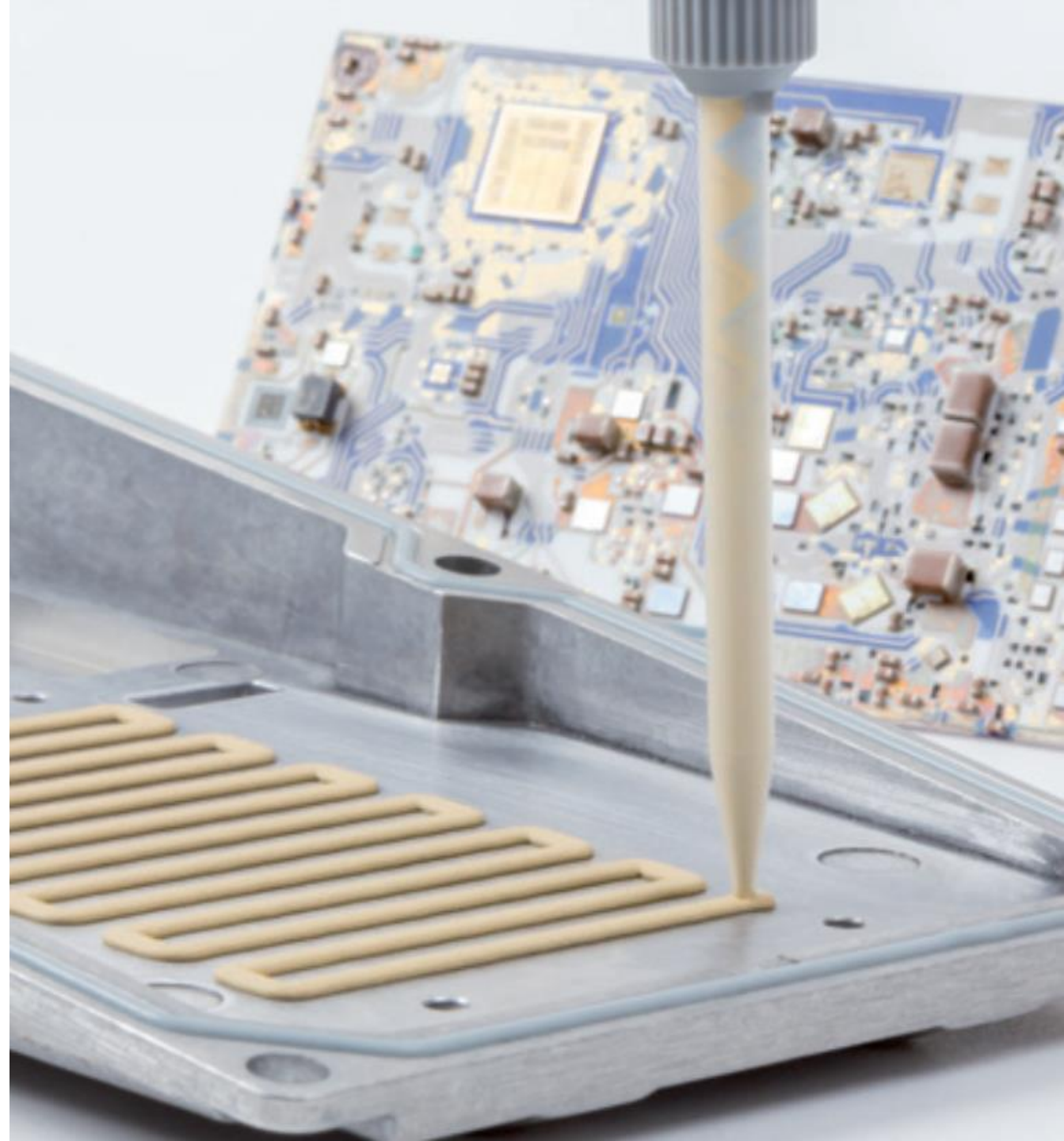


# Liquid Gap filler

2-componenten

Cure in place

- Silicone
- Non silicone (PU)



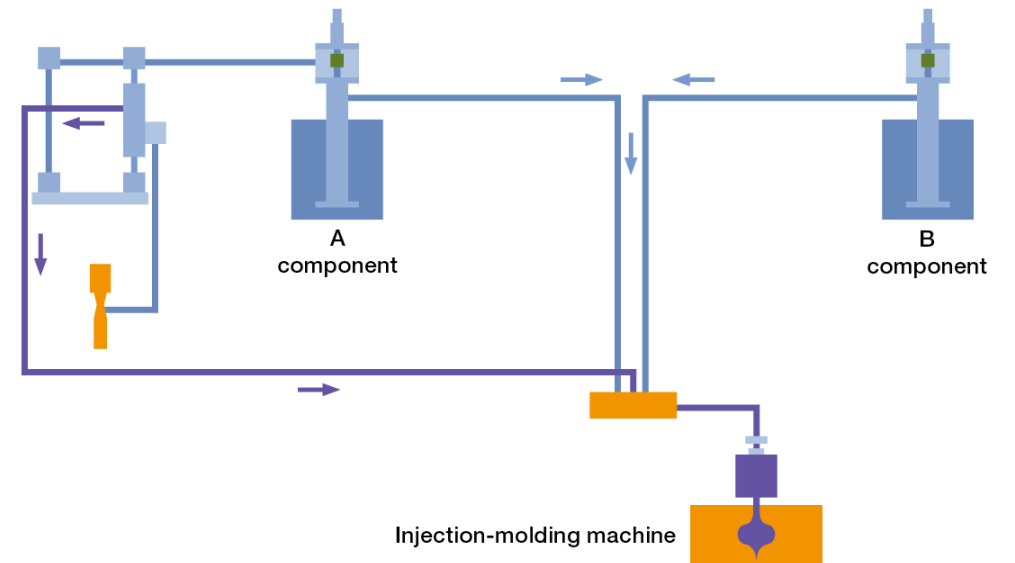
# Liquid gap filler applicatie



Dual cartridge 2x50ml, 2x200ml

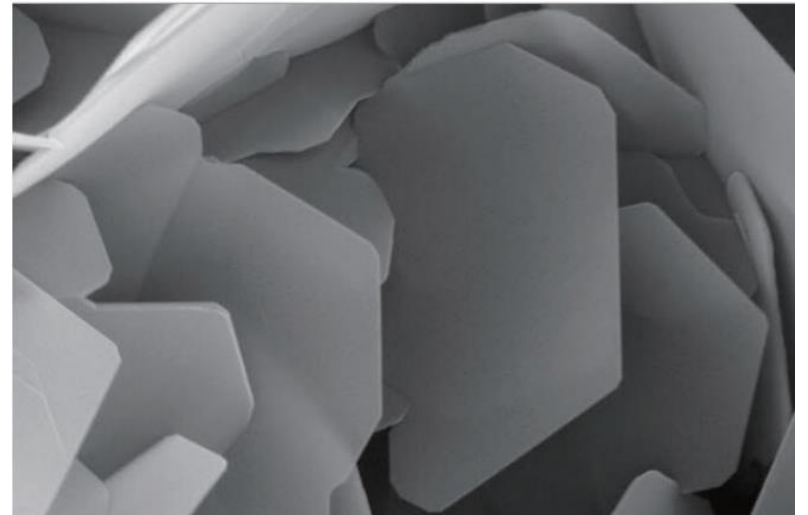
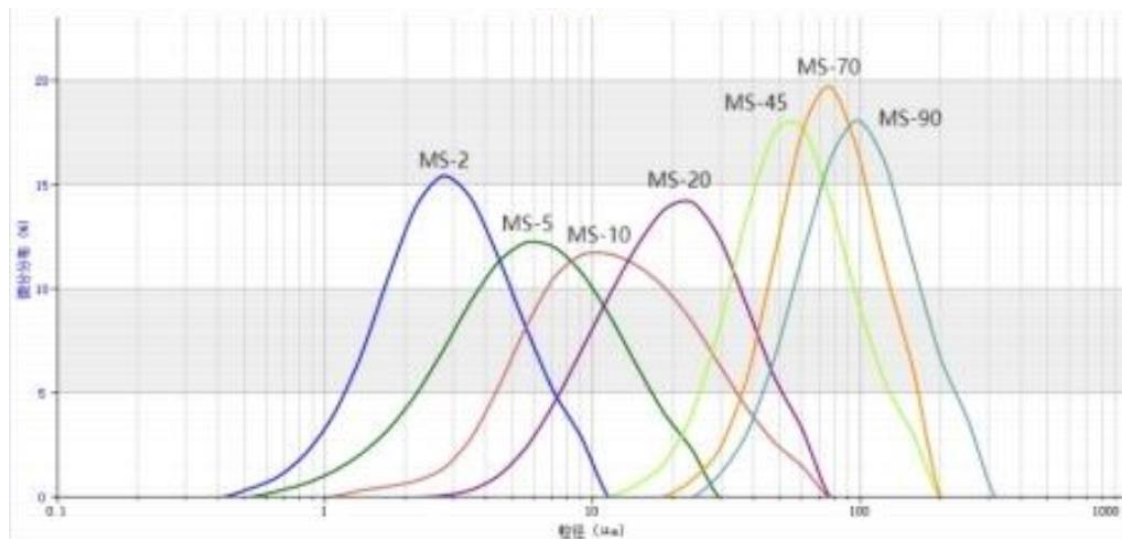
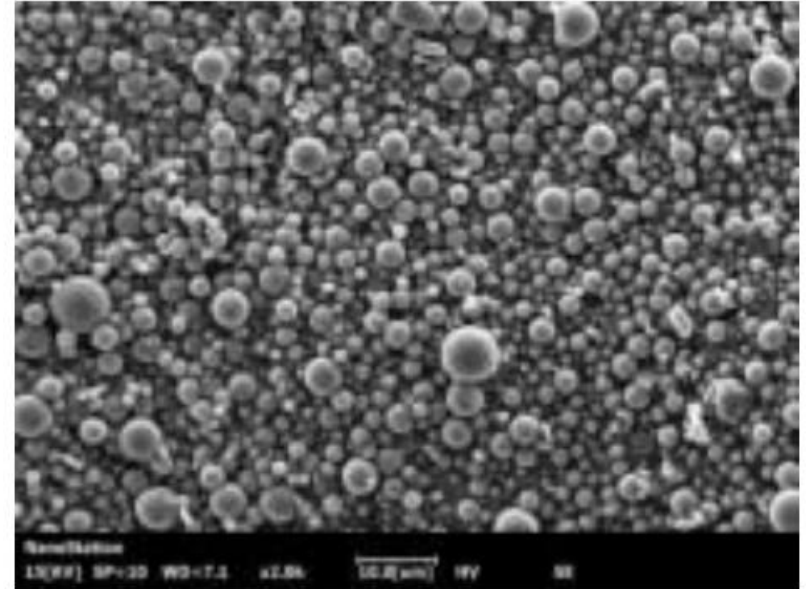
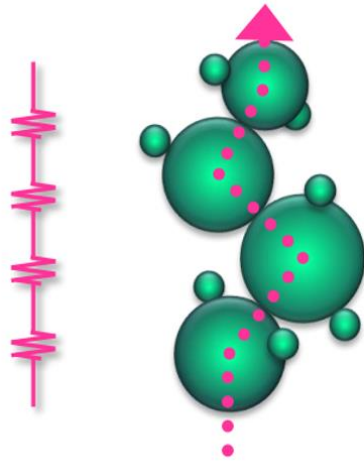


20kg bails or 200kg drums



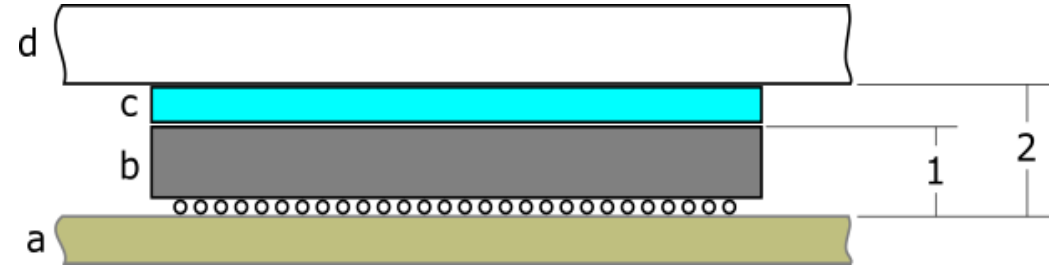
# Fillers in gap filler material

## Thermal Conductive Filler

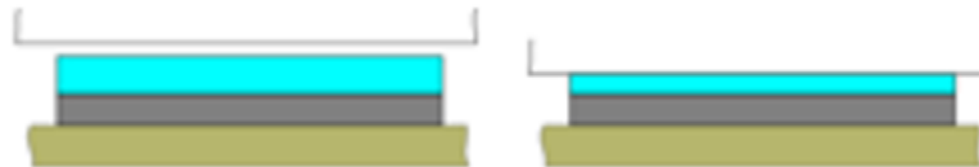




# Calculate the gap



- Example:
  - Gap filler pad compression between 10% and 40%
  - Gap filler tolerance thickness +/- 10%
  - Dimension 1 = 1.25mm +/- 0.15mm
  - Dimension 2 = 2.8 mm +/- 0.1mm
  - Calculated Gap (c) is minimum 1.3mm and max 1.8mm
  - A gap pad of 2.0 mm would fit best here
- Avoid airgap and avoid high compression force



# Pressure - Deflection - Thermal resistance

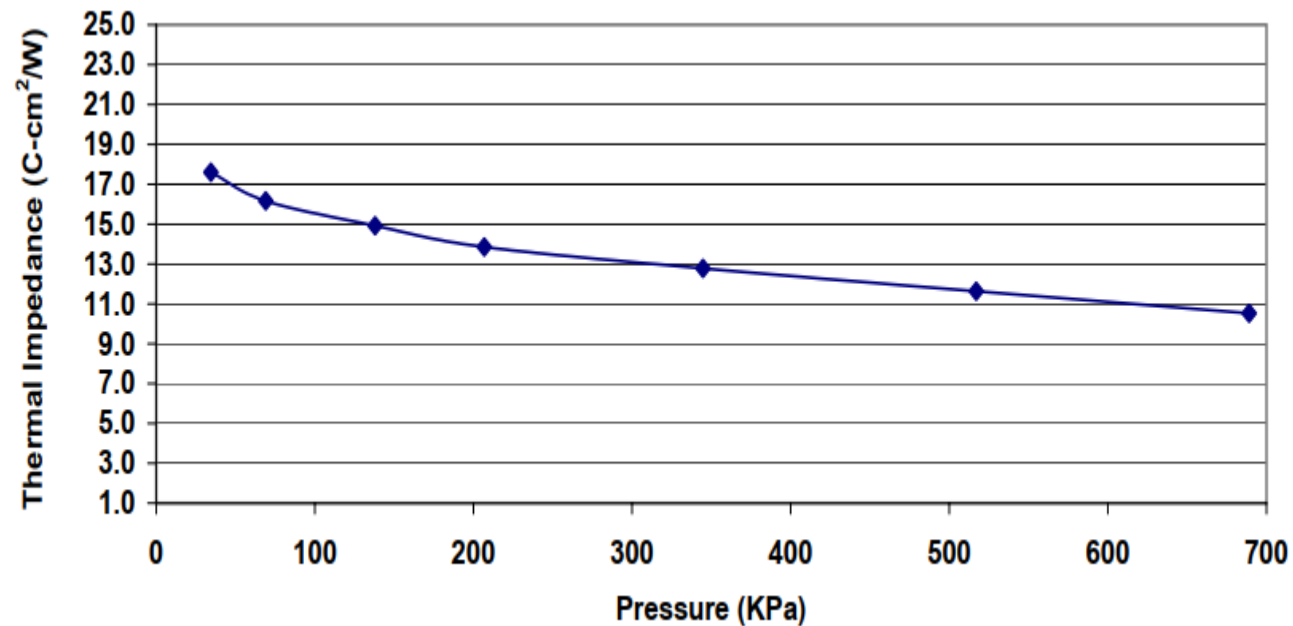
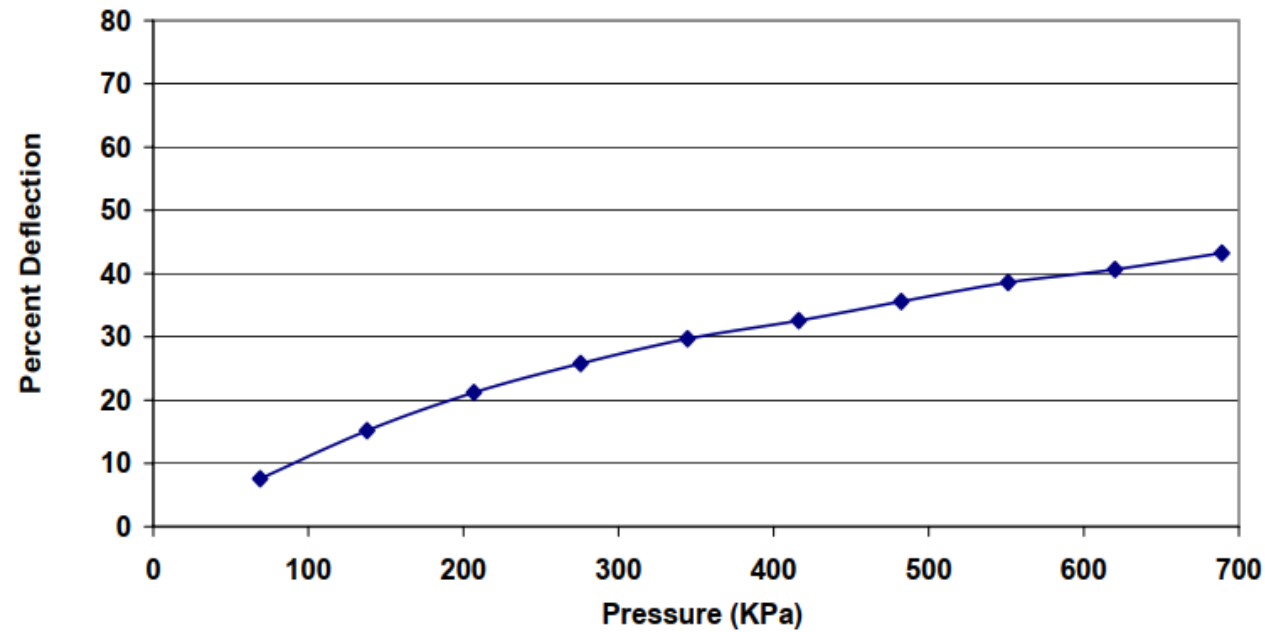
Typical 2.0 mm  
Silicone Gap filler  
Of 50 Shore 00

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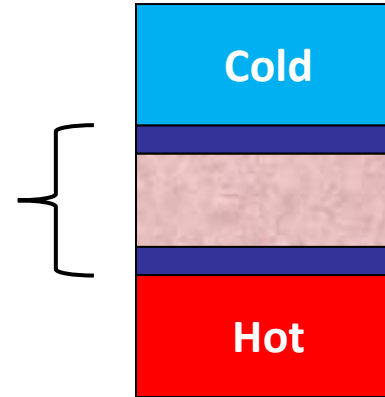
# Calculate the thermal resistance

Thermal interface resistance

$$R_{i1} = 1/Ah_{i1}$$

$$R_m = L/kA$$

$$R_{i2} = 1/Ah_{i2}$$



$$T_h - T_c = \dot{Q}_{12} * R_{int}$$

$$R_{int} = \frac{h'}{A} \quad h' = \text{thermal impedance}$$

Example component of 20mmx20mm, Gap filler of 0.51mm thickness

$$R_{int} = \frac{2.97}{2*2} = 1.19 \text{ K/W}$$

$$R_m = \frac{L}{kA} = \frac{0.51 * 10^{-3}}{3 * 20 * 20 * 10^{-6}}$$

$$R_m = 0.43 \text{ K/W} \rightarrow R_{i1} = R_{i2} = 0.38 \text{ K/W}$$

|  |  |
|--|--|
| Construction & Composition               | Reinforced boron nitride filled silicone elastomer       |
| Color                                    | Blue-Violet  |
| Thickness                                | 0.020" (0.51mm)  |
| Thickness Tolerance                      | ± 0.003" (± 0.08mm)                                      |
| Density                                  | 1.38 g/cc  |
| Hardness                                 | 40 Shore 00  |
| Tensile Strength                         | N/A  |
| % Elongation                             | N/A  |
| Outgassing TML (Post Cured)              | 0.13%  |
| Outgassing CVCM (Post Cured)             | 0.05%  |
| UL Flammability Rating                   | UL 94 V0   |
| Temperature Range                        | -45°C to 200°C   |
| Thermal Conductivity                     | 3 W/mK   |
| Thermal Impedance<br>@ 10 psi<br>@ 69KPa | 0.46 °C-in <sup>2</sup> /W<br>2.97 °C-cm <sup>2</sup> /W |
| Thermal Expansion                        | 600 ppm/°C   |
| Breakdown Voltage                        | 3,000 Volts AC   |
| Volume Resistivity                       | 2 x 10 <sup>13</sup> ohm-cm                              |
| Dielectric Constant @ 1MHz               | 3.31   |



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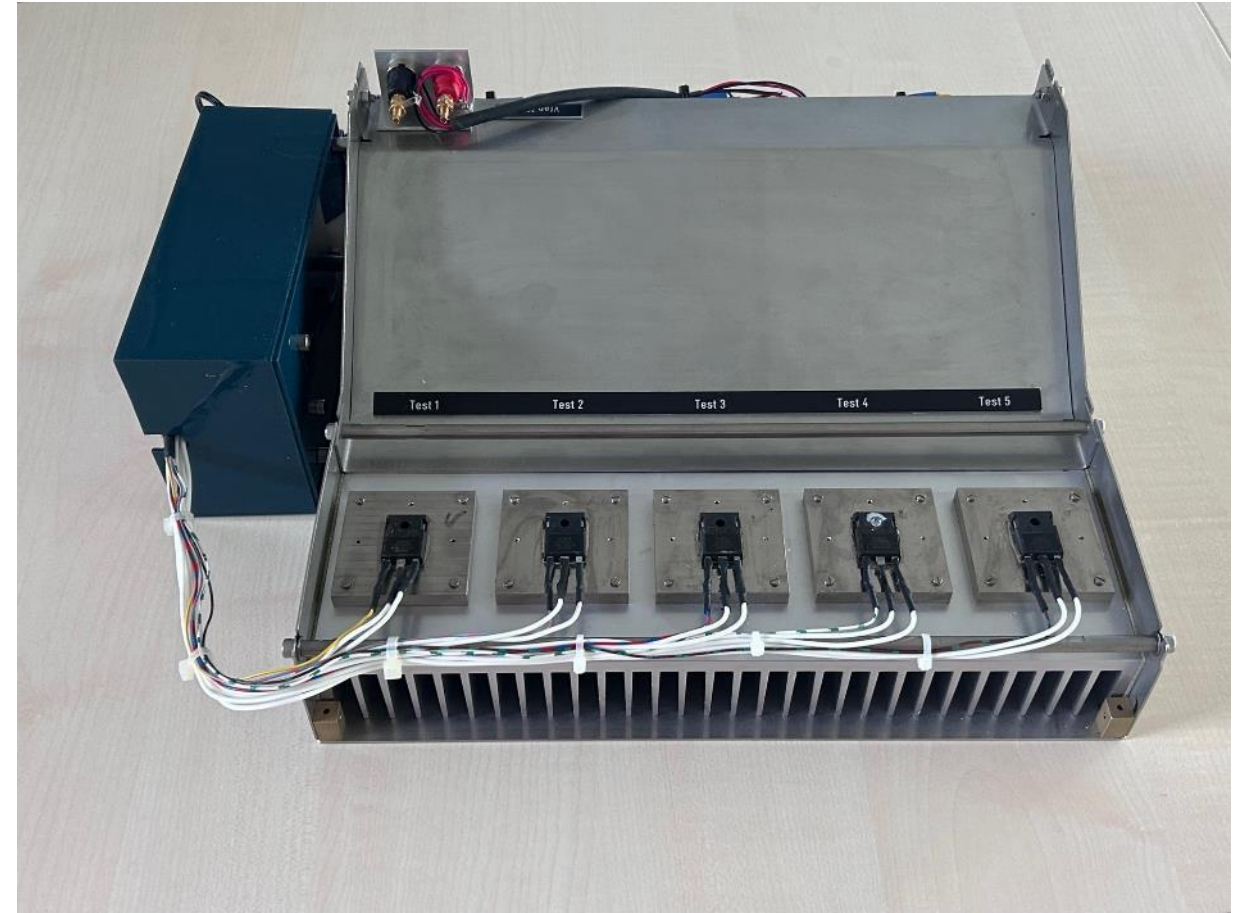
# Gap filler properties

- Silicone or Non-silicone material
- High deflection
- Cost Effective
- Electrically insulating
- Liquid gap filler can be abrasive or non/low abrasive
- Low bleed / Fogging
- Low / medium / high Thermal conductivity
- Softness/Hardness Shore 00
- Elastic/plastic behavior

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# Life Demo at exhibition

- Special thanks to Optical Thermal Solutions who provided this test setup for us.
- 5 different type of gap fillers life under test.
- Thermal load by FETs mounted on 50x50mm Copper plates
- Large Heatsink fan cooled to have maximum cooling, maximum  $\Delta T$
- $\Delta T$  visible on laptop screen



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## How can we help you?

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